

2A, 1000V Glass Passivated Bridge Rectifier

FEATURES

- Glass passivated junction
- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

MECHANICAL DATA

Case: Molded plastic body

Molding compound, UL flammability classification rating 94V-0 Moisture sensitivity level: level 1, per J-STD-020 Part no. with suffix "H" means AEC-Q101 qualified Packing code with suffix "G" means green compound (halogen-free) **Terminal:** Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 2 whisker test **Polarity:** Polarity as marked on the body **Weight:** 0.096 g (approximately)











PARAMETER		SYMBOL	ABS20M		UNIT	
Maximum repetitive peak reverse voltage			V _{RRM}	1000		V
Maximum RMS voltage		V _{RMS}	700		V	
Maximum DC blocking voltage		V _{DC}	1000		V	
Maximum average forward rectified current On glass-epoxy On aluminum substrate		I _{F(AV)}	1.6 2.0		A	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load		I _{FSM}	50		А	
Peak forward surge current, 1 ms single half $T_J=25^{\circ}C$ sine-wave superimposed on rated load $T_J=125^{\circ}C$		I _{FSM}	110 90		A	
Rating for fusing (t<8.3ms)		l ² t	10.375		A ² s	
				TYP	MAX	
	$I_F = 1 A T_J = T$	T _J =25°C		0.92	1.02	v
Maximum instantaneous forward voltage (Note 1)		T _J =125°C	V _F	0.80	-	
(1000-1)		T _J =25°C		-	1.10	
		T _J =125°C		0.94	-	
Maximum reverse current @ rated V_R		TJ=25°C		5		μΑ
		T _J =125°C	. I _R	150		
Typical thermal resistance			R _{θJL} R _{θJA}	30 85		°C/W
Operating junction temperature range			TJ	- 55 to +150		°C
Storage temperature range			T _{STG}	- 55 to +150		°C

Note 1: Pulse test with PW=300µs, 1% duty cycle



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ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE	PACKAGE	PACKING
SUFFIX		SUFFIX		
Ц	RE	G	ABS	1,000 / 7" Plastic reel
11	RG	9	ABS	5,000 / 13" Paper reel
	PART NO.	PART NO. PACKING CODE SUFFIX RE	PART NO.PACKING CODEPACKING CODESUFFIXSUFFIXSUFFIXHREG	PART NO.PACKING CODEPACKING CODEPACKAGESUFFIXREGABS

Note 1: Whole series with green compound

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ABS20MHREG	ABS20M	н	RE	G	AEC-Q101 qualified Green compound

100

RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)



AMBIENT TEMPERATURE (°C)





10 NUMBER OF CYCLES AT 60 Hz

FIG. 4 TYPICAL JUNCTION CAPACITANCE



PEAK FORWARD SURGE CURRENT (A)

10

0

1





PACKAGE OUTLINE DIMENSIONS

ABS



DIM.	Unit (mm)		Unit (inch)		
	Min	Max	Min	Max	
В	4.30	4.50	0.169	0.177	
С	6.25	6.65	0.246	0.262	
D	0.60	0.70	0.024	0.028	
E	3.90	4.10	0.154	0.161	
F	4.90	5.10	0.193	0.200	
G	1.40	1.60	0.055	0.063	
Н	1.35	1.45	0.053	0.057	
Ι	0.05	0.15	0.002	0.006	
J	0.30	0.70	0.012	0.028	
К	0.15	0.25	0.006	0.010	

GΗ



SUGGESTED	PAD LAYOUT	



P/N

YW

F

Symbol	Unit (mm)	Unit (inch)
A	1.50	0.059
В	0.90	0.035
С	4.22	0.166
D	7.22	0.284
E	2.05	0.081
F	5.72	0.225

MARKING DIAGRAM



- = Specific Device Code
- = Date Code
- = Factory Code



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